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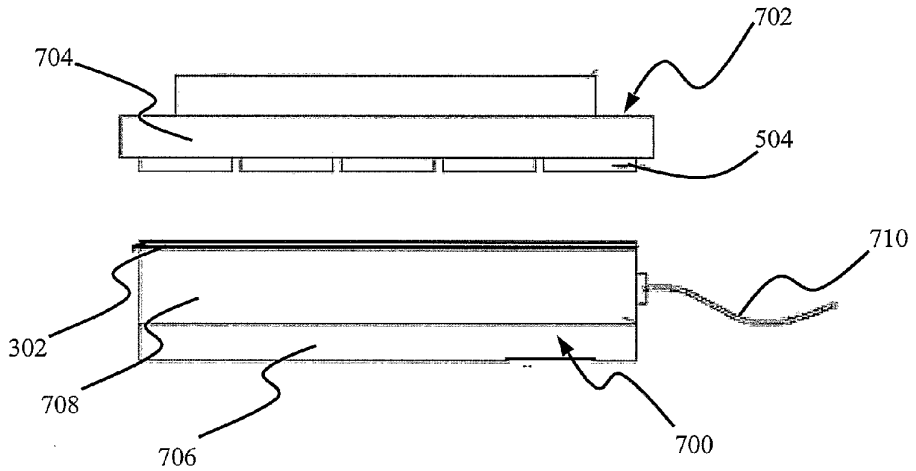
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(54) Title: SINGULATING AND DE-TAPPING ARRAYS OF SEMICONDUCTOR PACKAGES



(57) Abstract: An apparatus and method for separating at least one semiconductor package (504) formed on a substrate and a tape (302) removably adhered to the semiconductor package (504) are disclosed. The apparatus comprises a transferring unit (702) for engaging and displacing the semiconductor package (504) and a station (700) for disposing the semiconductor package (504) and the tape (302) thereon and for securing the tape (302). The semiconductor package (504) and the tape (302) are separable by initially the station (700) securing the tape (302) and providing thermal energy to the tape (302) for reducing the adhesion whereby the tape (302) is removably adhered to the semiconductor package (504) and subsequently the station (700) securing the tape (302) and the transferring unit (702) securing and displacing the semiconductor package (504) from the tape (302).

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